



Wafer-scale Nano- & Micro-optics for Lasers
and Integrated Photonics Applications

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EPIC Technology Meeting on Microelectronics
and Photonics – Two Sides of One Coin



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Wafer-scale Nano- & Micro-optics for Lasers and Integrated Photonics Applications

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12-Nov-2024



SCILS
Nanoimprint solutions



- ❑ Who we are
- ❑ Our production tools
- ❑ Imprint resists
- ❑ Nano Imprint Lithography – NIL
- ❑ Substrate Conformal Imprint Lithography – SCIL
- ❑ Current applications
- ❑ New applications
- ❑ Future applications
- ❑ Conclusions

Who we are

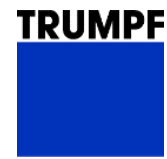
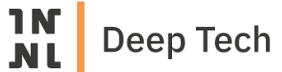
Start-up with strong financial partners

Solutions for volume production

Proven world-class technology



Building customer success - Together



LabSCIL

- R&D
- 100, 150 and 200mm wafers



AutoSCIL

- Integrated tool
- 100, 150 and 200mm wafers



FabSCIL

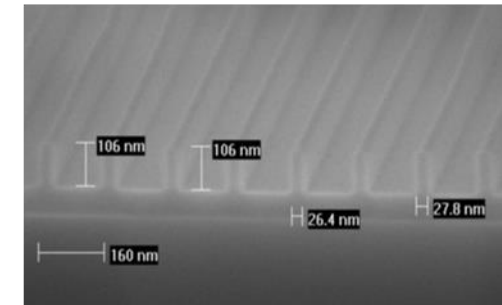
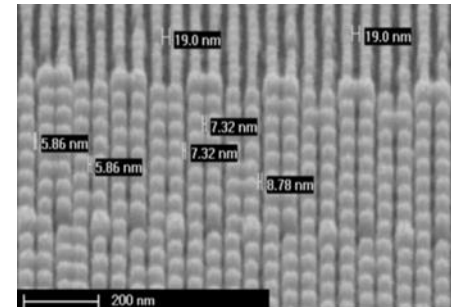
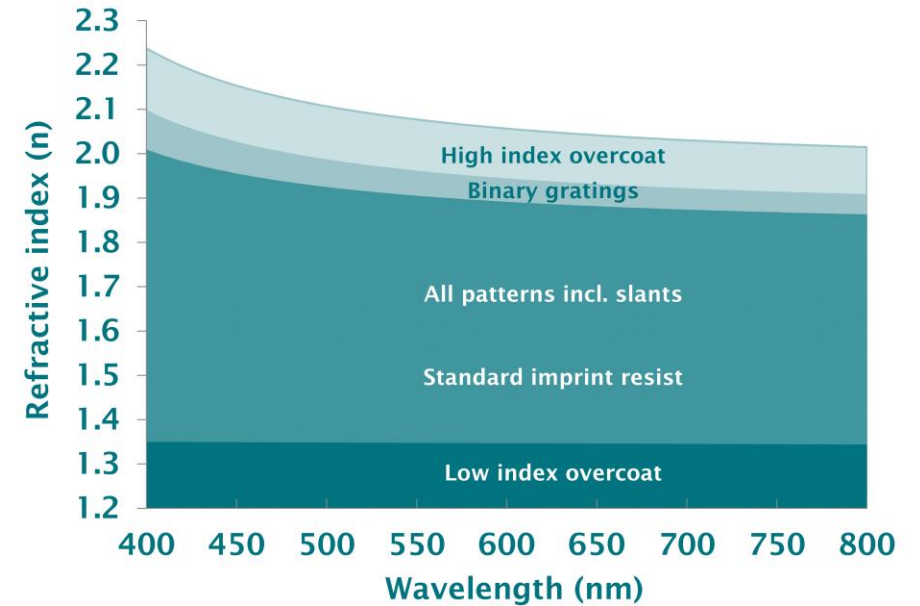
- Cluster design, freely configurable
- 150, 200 and 300mm wafers



All tools are capable of:

- Automatic (double side) overlay alignment
- Proprietary SCIL imprint process (seamless scaling)

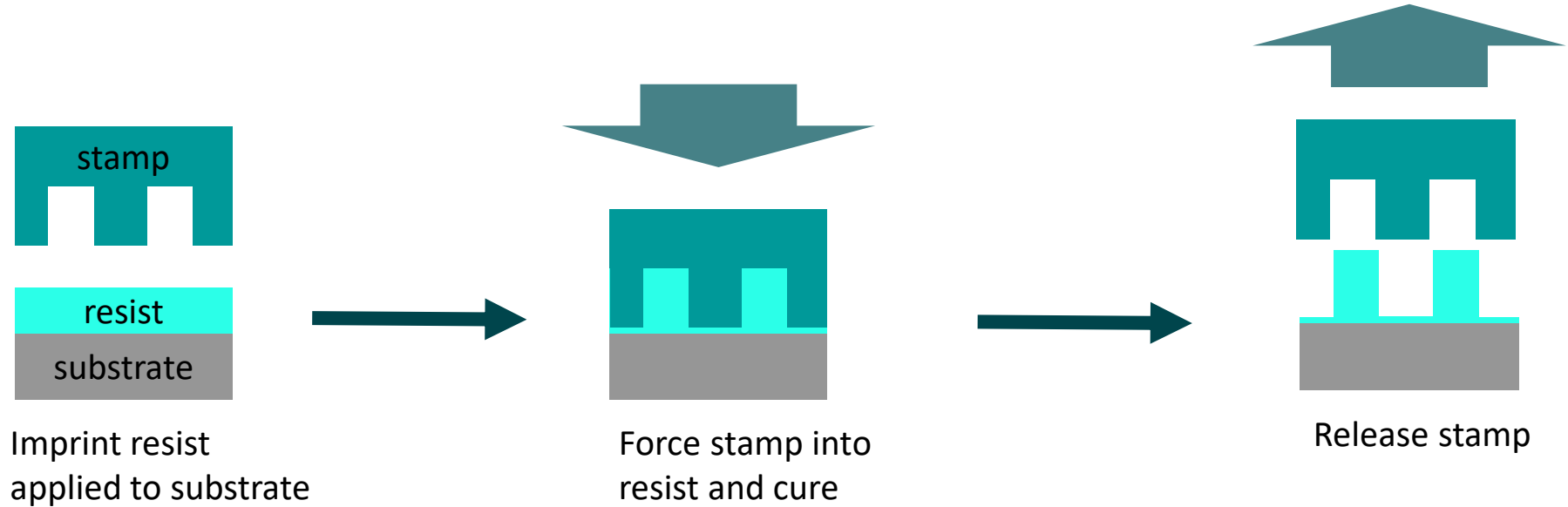
- **Proprietary imprint resist properties**
- Fully inorganic solgel based room temperature curing
- Low-shrinkage → < 10%
- Refractive index of 1.15 up to 2.2
- Feature sizes → Tens of microns down to 6 nm
- High aspect ratios
- Non-yellowing, no haze
- High temperature stability when cured → > 400 °C
- Insensitive to humidity UV when cured



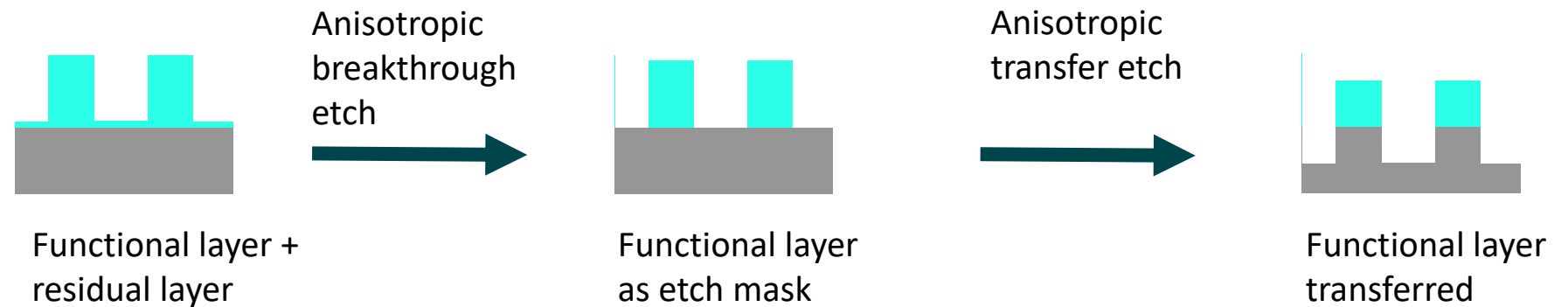
Etched quartz: 6 nm gaps

Nano Imprint Lithography - NIL

- Conventional NIL

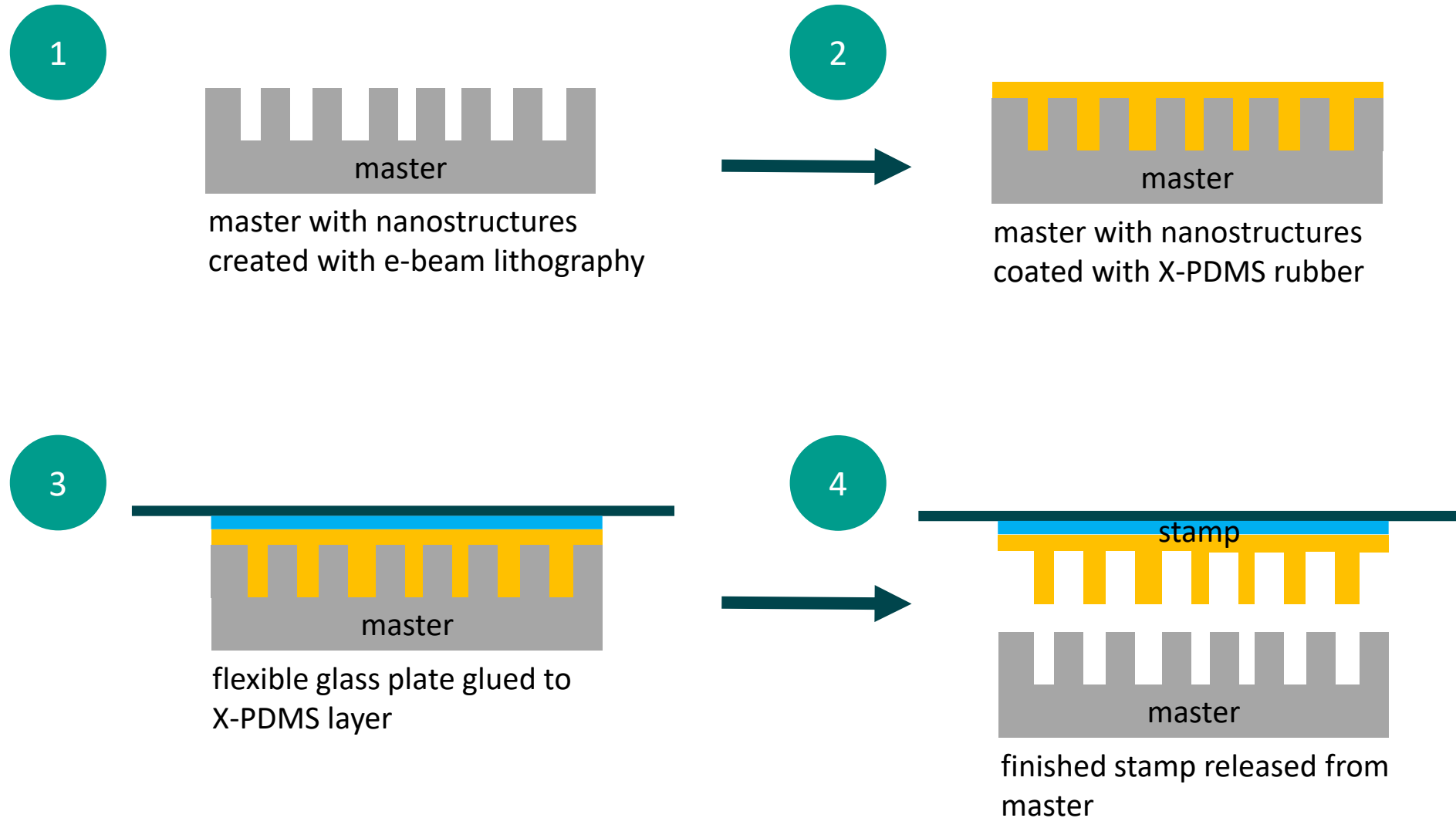


- NIL process for etch hard mask



Substrate Conformal Imprint Lithography - SCIL

- Stamp or mold creation
- 250+ stamps from 1 master
- 500+ imprints from 1 stamp
- 125k+ imprints from 1 master



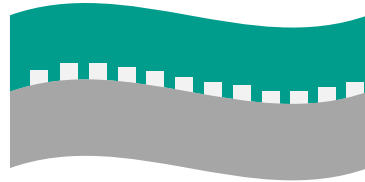
Substrate Conformal Imprint Lithography - SCIL

▪ Rigid quartz stamp

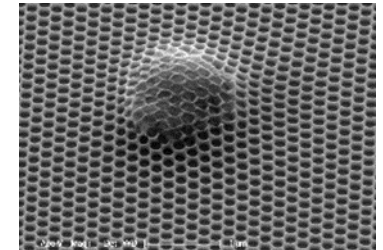
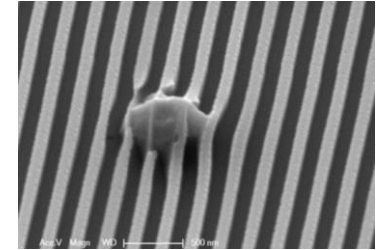


- + resolution
- + low pattern deformation
- low throughput
- need for release layer
- small contact area
- only organic resists
- sensitive to particles
- expensive stamps

▪ Soft rubber stamp



- resolution → X-PDMS: + resolution
- pattern deformation → SCIL: + low pattern deformation
- + high throughput
- + intrinsic non-sticking
- + wafer-scale conformal contact
- + organic + inorganic resists
- + insensitive to particles
- + low cost rubber stamps



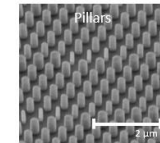
Substrate Conformal Imprint Lithography - SCIL

Sequential low pressure imprint cycle.
Capillary force driven.

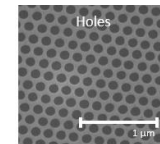
Sequential low force stamp
release



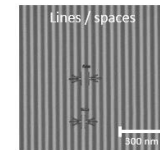
- Scalable technique
- Ultra-low pressure
- 3"-12" wafers demonstrated
- Scalable to larger areas
- Full automatic system
 - Imprint
 - Stamp release
- Low cost soft stamps
- Freedom of resist
 - Organic
 - Hybrid
 - Inorganic



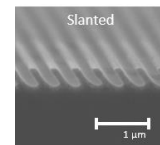
∅ 20 nm
↓ 1500 nm
↔ 30 nm pitch
aspect ratio: 10



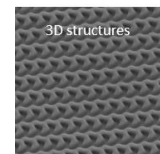
∅ 20 nm
↓ 1500 nm
↔ 50 nm pitch
aspect ratio: 3



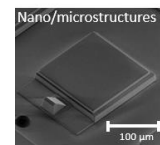
↔ 50 nm pitch
0.1 - 0.9 DC
↓ 1300 nm



∠45°
↓ 350 nm
↔ 300 nm period
0.33-0.66 DC



↓ 0-2000 nm
↔ 100nm – 20 microns
Multiple and continuous height levels



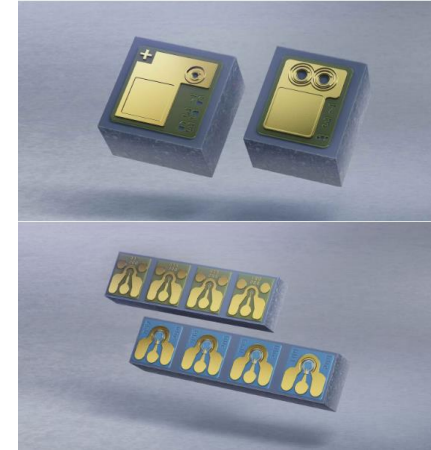
↓ up to 60 μm
Nano / micro patterns combination

TRUMPF



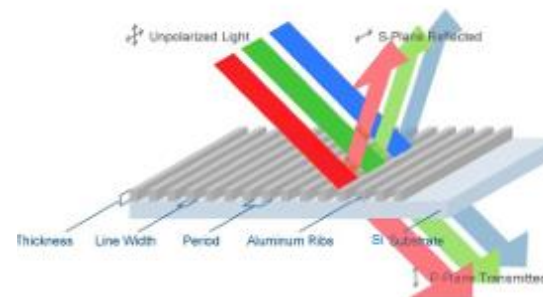
Vertical cavity surface emitting laser (VCSEL)

- III-V materials have inherent defects limiting optical litho
- SCIL is used for single-mode VCSELs since 2008 – present
- TRUMPF VCSEL and photodiodes: key components in data communication



Wiregrid polarizers

- 50/50 nm line/space
- Pixelated polarizers

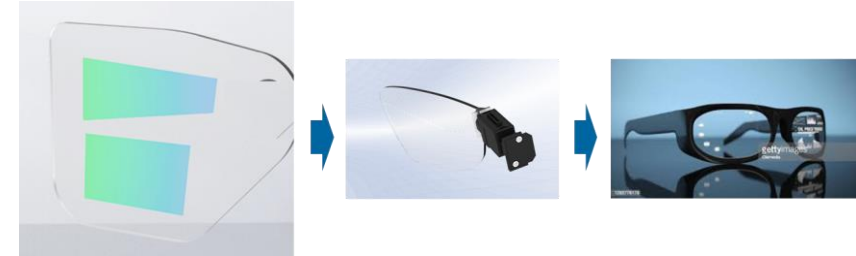


MOXTEK

undisclosed

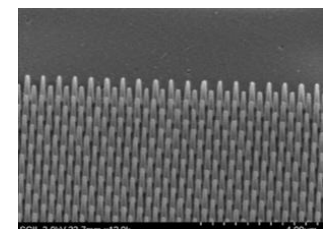
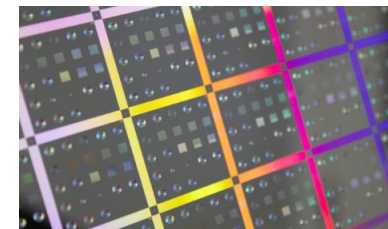
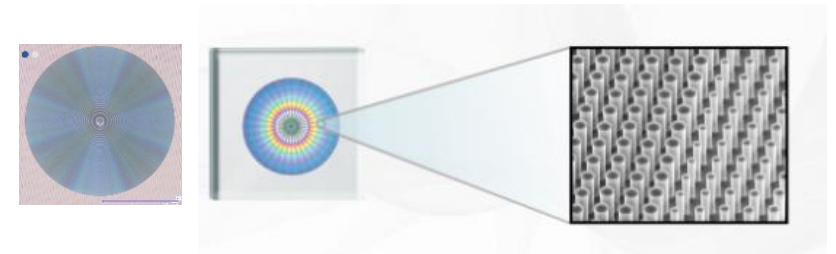
□ Waveguides for AR smartglass

- (Slanted) grating in high refractive material $\sim n=2$
- Double sided patterning with 500 nm overlay alignment accuracy



□ Metalens

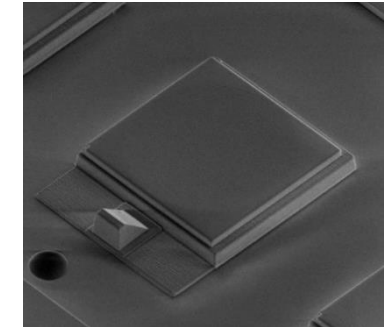
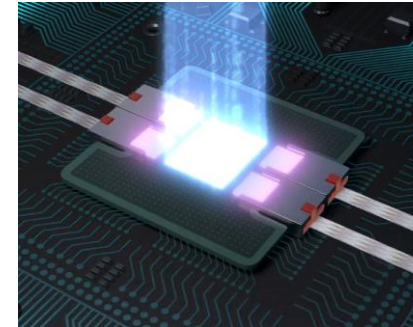
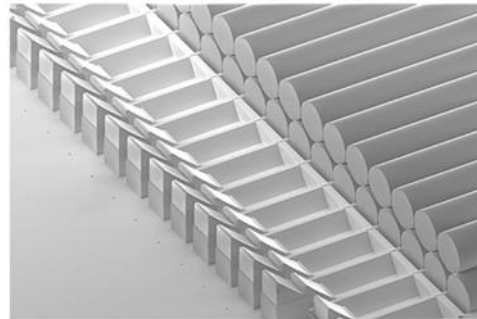
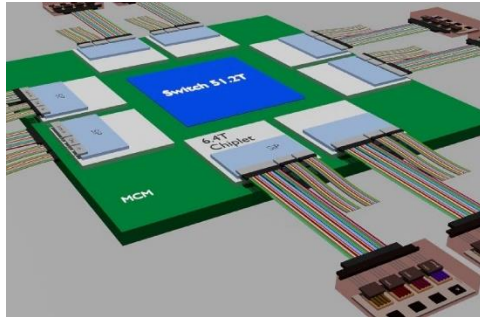
- High-performance metalenses for visible and IR wavelengths
- Full solution, including design, fabrication, measurement, and packaging capabilities at Moxtek



☐ Photonics Integrated Circuits

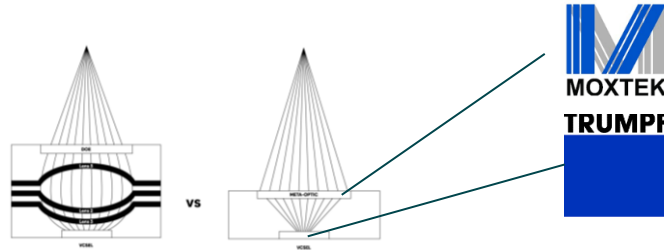


- The I/O bottleneck → Data transfer is limited by copper I/O's
- The connection between optics and silicon has not been reliable enough. Until now.
- SCIL is used to produce waveguides for the detachable glassfiber connection to silicon photonics chips, designed by Teramount



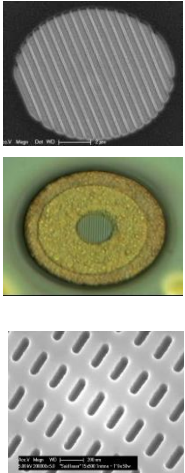
3D sensor for mobile phone

- Replacement of conventional lens with flat metalens single mode
- Polarizing grating to improve light efficiency of VCSEL laser



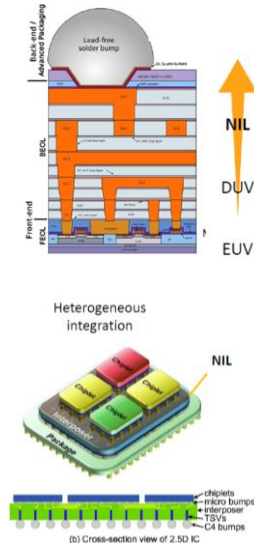
Photonic crystal surface emitting laser (PCSEL)

- scaling power output without sacrificing beam coherence
- single-mode operation over larger emission area



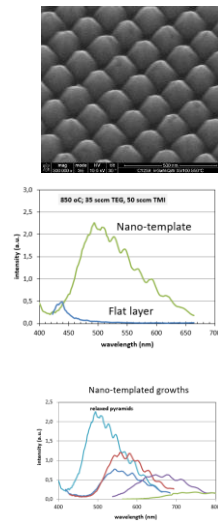
Added functionality on:

- semicon devices (color filters, polarizers, sensors)
- Chiplets/CPO (single- and multi-mode waveguides, through glass vias, high density interconnects)



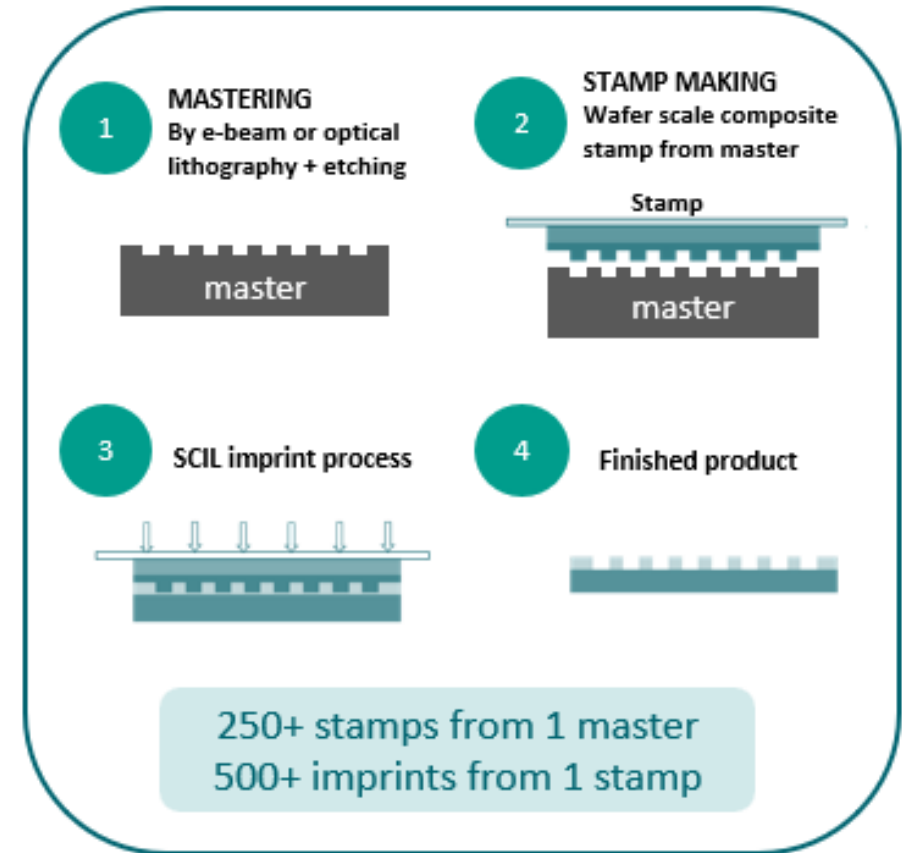
Direct growth of RGB LEDs on wafer

- Nano-templated InGaN growth → full nitride RGB system
- High temperature growth – better quality



Substrate Conformal Imprint Lithography

- Wafer scale nanoimprinting
- Sub-10 nm resolution
- Wafer scale overlay accuracy ~500nm
- High throughput, high yield
- Low costs
- For use as **hard etch mask** or **direct patterning functional materials**
 - Saving deposition and etch process steps
 - Creating new opportunities in a wide range of applications



- > 2.5 Million AR waveguides from one master
- > 1 Billion VCSEL lasers from one master
- > 300 Million Metalenses from one master

Interested in cooperating with SCIL?



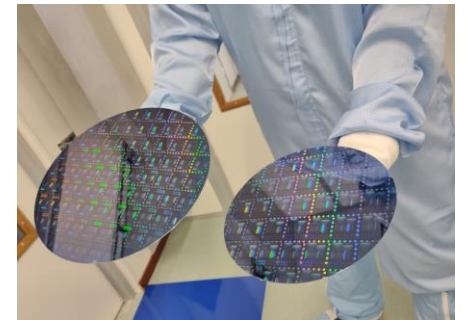
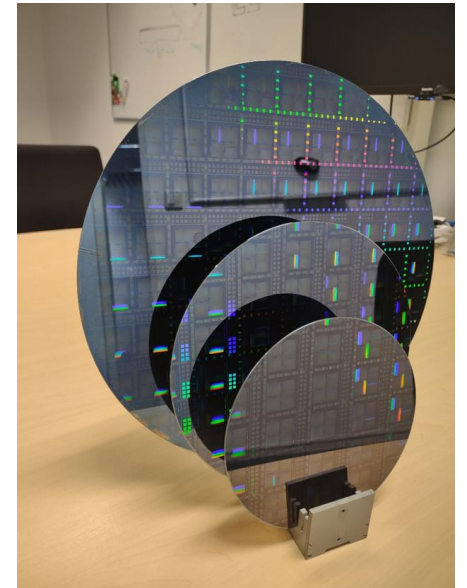
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